37. (Amended). The method of coating a substrate, the method comprising the step of applying an active coating material to the substrate to form an active coating layer, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and wherein the active coating material is applied electrostatically as a powder.

38. (Amended). The method according to claim 37, which further includes the step of removing the active coating layer from the substrate.

39. (Amended). The method according to claim 37, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

40. (Amended). The method according to claim 37, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer wherein the active coating layer is substantially completely covered by the cover coating layer, and wherein the cover coating layer is removable from the substrate.

41. (Amended). The method according to claim 40, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

42. (Amended). The method according to claim 40, wherein the cover coating layer is removable with the active coating layer.

43. (Amended). The method according to claim 40, wherein the cover material includes biologically active material.

Sub FS Cont.

44. (Amended). The method according to claim 40, wherein the method further includes the step of applying a further coating material to a surface of the substrate to form a further coating layer wherein the further coating layer is removable from the substrate.

C1 Cont

45. (Amended). The method according to claim 44, wherein the further coating material includes biologically active material, the further coating layer forming a further active coating layer and the method further includes the step of applying a further cover coating material onto the further active coating layer to form a further cover coating layer wherein the further active coating layer is substantially completely covered by the further cover coating layer and wherein the further cover coating layer is removable from the substrate.

46. (Amended). The method according to claim 45, wherein the active material of the active coating layer and the further active coating layer are the

same.

47. (Amended). The method according to claim 40, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer wherein the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

48. (Amended). The method according to claim 37 which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

49. (Amended). The method according to claim 48, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

50. (Amended). The method according to claim 37 wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

51. (Amended). The method according to claim 37 wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

52. (Amended). The method according to claim 37 wherein the method comprises supporting the substrate adjacent to the source of the active coating material with a surface of the substrate maintained at such a different electric potential from that of the active coating material that the application of the electric potential causes the active coating material to move from the source of the active coating material towards the substrate, a surface of the substrate becoming coated with the active coating material.

53. (Amended). The method according to claim 37 wherein the substrate is supported from above and the powder moves from the source upwards towards a lower surface of the substrate.

54. (Amended). The method according to claim 37 wherein the quantity of active material in the active coating applied to the substrate is substantially

equal to one dose of the active material.

55. (Amended). The method according to claim 37 wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

57. (Amended). The method according to claim 56, which further includes the step of removing the active coating layer from the substrate.

58. (Amended). The method according to claim 56, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

59. (Amended). The method according to claim 56, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer wherein the active coating layer is substantially completely covered by the cover coating layer, and wherein that cover coating layer is removable from the substrate.

60. (Amended). The method according to claim 59, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

61. (Amended). The method according to claim 59, wherein the cover coating layer is removable with the active coating layer.

62. (Amended). The method according to claim 59, wherein the cover material includes biologically active material.

Sw 55 cont.

63. (Amended). The method according to claim 59, wherein the method further includes the step of applying a further coating material to a surface of the substrate to form a further coating layer wherein the further coating layer is removable from the substrate.

C2 cont.

64. (Amended). The method according to claim 63, wherein the further coating material includes biologically active material, the further coating layer forming a further active coating layer and the method further includes the step of applying a further cover coating material onto the further active coating layer to form a further cover coating layer wherein the further active coating layer is substantially completely covered by the further cover coating layer and wherein the further cover coating layer is removable from the substrate.

65. (Amended). The method according to claim 64, wherein the active material of the active coating layer and the further active coating layer are the

same.

66. (Amended). The method according to claim 59, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer wherein the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

67. (Amended). The method according to claim 56, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

68. (Amended). The method according to claim 67, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

69. (Amended). The method according to claim 56, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

70. (Amended). The method according to claim 56, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

71. (Amended). The method according to claim 56, wherein the method comprises supporting the substrate adjacent to source of the active coating material with a surface of the substrate maintained at such a different electric potential from that of the active coating material that the application of the electric potential causes the active coating material to move from the source of the active coating material towards the substrate, a surface of the substrate becoming coated with the active coating material.

72. (Amended). The method according to claim 56, wherein the substrate is supported from above and the powder moves from the source upwards towards a lower surface of the substrate.

73. (Amended). The method according to claim 56, wherein the quantity of active material in the active coating applied to the substrate is substantially

equal to one dose of the active material.

74. (Amended). The method according to claim 56, wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

76. (Amended). The method according to claim 75, which further includes the step of removing the active coating layer from the substrate.

77. (Amended). The method according to claim 75, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

78. (Amended). The method according to claim 75, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer wherein the active coating layer is substantially completely covered by the cover coating layer, and wherein that cover coating layer is removable from the substrate.

79. (Amended). The method according to claim 78, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

80. (Amended). The method according to claim 78, wherein the cover coating layer is removable with the active coating layer.

81. (Amended). The method according to claim 78, wherein the cover material includes biologically active material.

82. (Amended). The method according to claim 78, wherein the method further includes the step of ~~applying a~~ further coating material to a surface of the substrate to form a further ~~coating~~ layer wherein the further coating layer is removable from the substrate.

C3 Cont

83. (Amended). The method according to claim 82, wherein the further coating material includes biologically active material, the further coating layer forming a further active coating layer and the method further includes the step of applying a further cover coating material onto the further active coating layer to form a further cover coating layer wherein the further active coating layer is substantially completely covered by the further cover coating layer and wherein the further cover coating layer is removable from the substrate.

84. (Amended). The method according to claim 83, wherein the active material of the active coating layer and the further active coating layer are the

same.

85. (Amended). The method according to claim 78, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer wherein the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

C3 Cont

86. (Amended). The method according to claim 75, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

87. (Amended). The method according to claim 86, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

88. (Amended). The method according to claim 75, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

89. (Amended). The method according to claim 75, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

90. (Amended). The method according to claim 75, wherein the method comprises supporting the substrate adjacent to source of the active coating material with a surface of the substrate maintained at such a different electric potential from that of the active coating material that the application of the electric potential causes the active coating material to move from the source of the active coating material towards the substrate, a surface of the substrate becoming coated with the active coating material.

C3 cont

91. (Amended). The method according to claim 75, wherein the substrate is supported from above and the powder moves from the source upwards towards a lower surface of the substrate.

92. (Amended). The method according to claim 75, wherein the active coating material is applied to a plurality of individual regions on the surface of the

substrate.

94. (Amended). The method according to claim 93, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer wherein the active coating layer is substantially completely covered by the cover coating layer, and wherein that cover coating layer is removable from the substrate, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

C4

95. (Amended). The method according to claim 93, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

96. (Amended). The method according to claim 93, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

97. (Amended). The method according to claim 93 wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

98 (Amended). A method of coating a substrate using a coating apparatus, the method including the steps of applying an active coating material to the substrate to form an active coating layer, said substrate being a surface of the coating apparatus, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and wherein the active coating is removed as a wafer.

99. (Amended). The method according to claim 98 wherein the active material is applied to a conveyor belt.

100. (Amended). The method according to claim 98, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

101. (Amended). The method according to claim 98, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer wherein the active coating layer is substantially completely covered by the cover coating layer, and wherein that cover coating layer is removable from the substrate.

102. (Amended). The method according to claim 101, wherein the cover coating material is applied electrostatically as a powder and after application is

fused to form a cover film coating.

103. (Amended). The method according to claim 101, wherein the cover coating layer is removable with the active coating layer.

104. (Amended). The method according to claim 101, wherein the cover material includes biologically active material

105. (Amended). The method according to claim 101, wherein the method further includes the step of applying a further coating material to a surface of the substrate to form a further coating layer wherein the further coating layer is removable from the substrate.

C4 cont

106. (Amended). The method according to claim 105, wherein the further coating material includes biologically active material, the further coating layer forming a further active coating layer and the method further includes the step of applying a further cover coating material onto the further active coating layer to form a further cover coating layer wherein the further active coating layer is substantially completely covered by the further cover coating layer and wherein the further cover coating layer is removable from the substrate.

107. (Amended). The method according to claim 106, wherein the active

material of the active coating layer and the further active coating layer are the same.

108. (Amended). The method according to claim 101, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer wherein the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

C4 cont

109. (Amended). The method according to claim 98, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

110. (Amended). The method according to claim 109, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

111. (Amended). The method according to claim 98, wherein the method comprises supporting the substrate adjacent to source of the active coating material with a surface of the substrate maintained at such a different electric potential from that of the active coating material that the application of the electric potential causes the active coating material to move from the source of the active coating material towards the substrate, a surface of the substrate becoming coated with the active coating material.

112. (Amended). The method according to claim 98, wherein the substrate is supported from above and the powder moves from the source upwards towards a lower surface of the substrate.

C4 cont

113. (Amended). The method according to claim 98, wherein the quantity of active material in the active coating applied to the substrate is substantially equal to one dose of the active material.

114. (Amended). The method according to claim 98, wherein the wafer removed from the coated substrate is a solid dosage form.

115. (Amended). The method according to claim 98, wherein the active coating material is applied to a plurality of individual regions on the surface of the

substrate.

116. (Amended). The method according to claim 98 wherein the active coating material is applied as a liquid and after the active coating layer is applied the active coating material is treated to form an active film coating.

117. (Amended). The method according to claim 116, wherein a predetermined number of droplets of active coating material are applied to the surface of the substrate.

118. (Amended). The method according to claim 116, wherein an ink jet head is used to apply coating material to the substrate.

C4 Cont

119. (Amended). The method according to claim 116, wherein the active coating material is applied in the form of individual liquid droplets of liquid directly towards a surface of the substrate.

120 (Amended). A method of coating a substrate using a coating apparatus, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, said substrate being a surface of the coating apparatus, the active coating material comprising biologically active material, wherein the active coating layer is removable from the

substrate, and the active coating material is applied electrostatically as a powder, and wherein the active coating is removed as a wafer.

121. (Amended). The method according to claim 120, wherein the active material is applied to a conveyor belt.

122. (Amended). The method according to claim 120, wherein the substrate is pre-coated with one or more coating layers removable from the substrate and the active coating layer is removable therewith.

123. (Amended). The method according to claim 120, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer wherein the active coating layer is substantially completely covered by the cover coating layer, and wherein that cover coating layer is removable from the substrate, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

124. (Amended). The method according to claim 123, wherein the cover coating layer is removable with the active coating layer.

125. (Amended). The method according to claim 123, wherein the cover

material includes biologically active material

126. (Amended). The method according to claim 123, wherein the method further includes the step of applying a further coating material to a surface of the substrate to form a further coating layer wherein the further coating layer is removable from the substrate.

Sub RS Cont.

127. (Amended). The method according to claim 126, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer wherein the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

C4 Cont.

128. (Amended). The method according to claim 120, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

129. (Amended). The method according to claim 128, wherein the base coating layer and the cover coating layer are each applied electrostatically as a powder and each fused to form a film.

130. (Amended). The method according to claim 120, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

131. (Amended). The method according to claim 120, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

132. (Amended). The method according to claim 120, wherein the quantity of active material in the active coating applied to the substrate is substantially equal to one dose of the active material.

133. (Amended). The method according to claim 120, wherein the wafer removed from the coated substrate is a solid dosage form.

134. (Amended). The method according to claim 120, wherein the active coating material is applied to a plurality of individual regions on the surface of the

substrate.

135 (Amended). A method of coating a substrate using a coating apparatus, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, said substrate being a surface of the coating apparatus, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and the active coating material is applied electrostatically as a powder, and wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate, and wherein the active coating is removed as a wafer.

136. (Amended). The method according to claim 135, wherein the active material is applied to a conveyor belt.

137. (Amended). The method according to claim 135, which further includes the step of applying a cover coating material onto the active coating layer to form a cover coating layer wherein the active coating layer is substantially completely covered by the cover coating layer, and wherein that cover coating layer is removable from the substrate, and wherein the cover coating material is applied electrostatically as a powder and after application is fused to form a cover film coating.

138. (Amended). The method according to claim 137, wherein the method includes the step of applying a second active coating layer onto a surface of the substrate, the second active coating layer forming a second active coating region on the surface of the substrate, the second active coating layer being removable from the substrate, and applying a second cover coating layer onto the second active coating layer to form a second cover coating layer wherein the second active coating layer is substantially completely covered by the second cover coating layer, the second cover coating layer being substantially separate from the first cover coating layer, and being removable from the substrate.

139. (Amended). The method according to claim 135, which comprises applying to the substrate a base coating layer, applying the active material to the base layer and applying a cover coating layer over the active coating layer, the three layers being removable together by peeling from the substrate in the form of a three-layer wafer.

140. (Amended). The method according to claim 139, wherein the base coating layer and the cover coating layer are each applied as a powder and each fused to form a film.

141. (Amended). The method according to claim 135, wherein at least

90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

142. (Amended). The method according to claim 135, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

143. (Amended). The method according to claim 135, wherein the quantity of active material in the active coating applied to the substrate is substantially equal to one dose of the active material.

144. (Amended). The method according to claim 135, wherein the wafer removed from the coated substrate is a solid dosage form.

145. (Amended). The method according to claim 135 wherein the active coating material is applied to a plurality of individual regions on the surface of the substrate.

148. (Amended). A method of coating a plurality of coating regions onto the surface of a substrate, the method comprising the steps of:

(a) applying an active coating material to a surface of the substrate to form

a plurality of active coating regions on the surface comprising active coating layers, the active coating material comprising biologically active material and being applied electrostatically as a powder,

(b) applying a cover coating material to a surface of the substrate to form a plurality of cover coating regions, the cover coating regions forming layers of cover coating material, each active coating region being substantially completely covered by a cover coating region, wherein each region of active coating and cover coating is removable from the surface of the substrate.

149. (Amended). The method according to claim 148, wherein after the active coating material is applied the active coating material is fused to form regions of active film coating on the surface of the substrate.

C5 Cont

150. (Amended). The method according to claim 148, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form regions of cover film coating.

Sub FS

151. (Amended). The method according to claim 148, the method including the step of removing the active coating regions from the substrate to form wafers comprising active material.

152. (Amended). The method according to claim 148, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

153. (Amended). The method according to claim 148, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

154. (Amended). A method of coating a plurality of coating regions onto the surface of a substrate using a coating apparatus, the method comprising the steps of:

(a) applying an active coating material to a surface of the substrate to form a plurality of active coating regions on the surface comprising active coating layers, said substrate being a surface of the coating apparatus, the active coating material comprising biologically active material;

(b) applying a cover coating material to a surface of the substrate to form a plurality of cover coating regions, the cover coating regions forming layers of cover coating material, each active coating region being substantially completely covered by a cover coating region, wherein each region of active coating and cover coating is removable from the surface of the substrate, and wherein the active coating regions are removed as wafers.

155. (Amended). The method according to claim 154, wherein the active material is applied to a conveyor belt.

156. (Amended). A method of coating a plurality of coating regions onto the surface of a substrate using a coating apparatus, the method comprising the steps of:

(a) applying an active coating material to a surface of the substrate to form a plurality of active coating regions on the surface comprising active coating layers, said substrate being a surface of the coating apparatus, the active coating material comprising biologically active material and being applied electrostatically as a powder,

(b) applying a cover coating material to a surface of the substrate to form a plurality of cover coating regions, the cover coating regions forming layers of cover coating material, each active coating region being substantially completely covered by a cover coating region, wherein each region of active coating and cover coating is removable from the surface of the substrate, and wherein the active coating regions are removed as wafers.

157. (Amended). The method according to claim 156, wherein after the active coating material is applied the active coating material is fused to form

regions of active film coating on the surface of the substrate.

158. (Amended). The method according to claim 156, wherein the cover coating material is applied electrostatically as a powder and after application is fused to form regions of cover film coating.

159. (Amended). The method according to claim 156, wherein the active material is applied to a conveyor belt.

160. (Amended). The method according to claim 156, wherein at least 90% by weight of the particles of the active coating material have a particle size in the range of from 1 to 45 microns.

161. (Amended). The method according to claim 156, wherein 90% by weight of the particles have a size less than 70 microns, 50% by weight have a size less than 40 microns and 10% by weight have a size less than 10 microns.

163. (Amended). The method according to claim 162, wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate.

164. (Amended). The method according to claim 162, wherein active

coating material is applied to a plurality of individual regions on the surface of the substrate.

165. (Amended). The method according to claim 164, wherein the amount of active coating material deposited on a given area of the substrate is controlled such that the product can subsequently be divided into portions with each portion containing a pre-determined amount of active coating material, each pre-determined amount being one dose of the active material.

166 (Amended). A method of coating a substrate using a coating apparatus, the method including the steps of applying an active coating material to the substrate to form an active coating layer, said substrate being a surface of the coating apparatus, the active coating material comprising biologically active material, wherein the active coating layer is removable from the substrate, and wherein the active coating is removed as a wafer and divided into smaller portions.

167 (Amended). A method of coating a substrate using a coating apparatus, the method comprising the steps of applying an active coating material to the substrate to form an active coating layer, said substrate being a surface of the coating apparatus, the active coating material comprising biologically active material, wherein the active coating layer is removable from the

substrate, and the active coating material is applied electrostatically as a powder, and wherein the active coating is removed as a wafer and divided into smaller portions.

C6 cont

168. (Amended). The method according to claim 167, wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate.

C7

170. (Amended). The method according to claim 169, wherein after the active coating layer is applied the active coating material is fused to form an active film coating on the surface of the substrate.

172. (Amended). The coated substrate according to claim 171, wherein the active coating layer is a fused film layer.

C8

173. (Amended). The coated substrate according to claim 171, the substrate further including a cover coating layer on a surface of the substrate, the cover coating layer substantially completely covering the active coating layer wherein the cover coating layer is removable from the substrate together with the active coating layer or separately.

174. (Amended). The coated substrate according to claim 173, wherein

the cover coating layer is a fused film layer which has been applied electrostatically as a powder and fused.

175. (Amended). The coated substrate according to claim 173, wherein the cover coating layer includes biologically active material.

176. (Amended). The coated substrate according to claim 171, wherein the quantity of biologically active material on the substrate is substantially equal to one dose of the biologically active material.

177. (Amended). The coated substrate according to claim 171, wherein the active coating layer removed from the substrate constitutes a solid dosage form.

C8 Cont

178. (Amended). The coated substrate according to claim 171, wherein the active coating layer comprises

i) a continuous phase component

ii) the biologically active material

iii) a charge-modifying component and

iv) a flow aid.

C9

180. (Amended). The intermediate product according to claim 179,

wherein the active coating is fused.

Sub D18 181 (Amended). An intermediate product for use in producing a plurality of solid dosage forms, the intermediate product comprising a substrate and active coating comprising biologically active material in a plurality of regions on the substrate, the active coating regions being removable from the surface of the substrate, wherein each active coating region includes a cover coating region comprising a layer of cover coating material, each active coating region being substantially completely covered by a cover coating region and wherein each region of active coating and cover coating is removable from the surface of the substrate, wherein the active coating has been applied electrostatically as a powder.

C9 cont

Sub D19 183 (Amended). An intermediate product for use in producing a plurality of solid dosage forms, the intermediate product comprising a substrate and active coating comprising biologically active material in a plurality of regions on the substrate, the active coating regions being removable from the surface of the substrate, wherein each active coating region includes a cover coating region comprising a layer of cover coating material, each active coating region being substantially completely covered by a cover coating region and wherein each region of active coating and cover coating is removable from the surface of the substrate, wherein the active coating layer comprises:

C10

i) a continuous phase component;

ii) the biologically active material;

iii) a charge-modifying component; and

iv) a flow aid.

C10 cont

185 (Amended). The intermediate product according to claim 184, wherein the active coating material is fused.

C11 Sub FS

186 (Amended). The intermediate product according to claim 184, which is a three-layer wafer comprising an active material layer sandwiched between two non-active layers.

Please add the following new claims.

187 (New). A coated substrate comprising an active coating layer applied on a surface of the substrate, the substrate being a conveyor belt, and the active coating layer including biologically active material, and in which the coating layer is removable from the surface of the coated substrate.

C12

188 (New). An intermediate product for use in producing a plurality of solid dosage forms, the intermediate product comprising a substrate and active coating comprising biologically active material in a plurality of regions on the

substrate, the substrate being a conveyor belt, each region of active coating being removable from the surface of the substrate.

189 (New). An intermediate product for use in producing a plurality of solid dosage forms, the intermediate product comprising a substrate and active coating comprising biologically active material in a plurality of regions on the substrate, the substrate being a conveyor belt, the active coating regions being removable from the surface of the substrate, wherein each active coating region includes a cover coating region comprising a layer of cover coating material, each active coating region being substantially completely covered by a cover coating region and such that each region of active coating and cover coating is removable from the surface of the substrate.

C 12 cont

190 (New). An intermediate product for use in producing a plurality of solid dosage forms, the intermediate product comprising a substrate and active coating material comprising biologically active material on the substrate, the substrate being a conveyor belt, the amount of active coating material on a given area of the substrate that the product can subsequently be divided into portions with each portion containing a predetermined amount of active coating material, each predetermined amount being one dose of the active material, and the active coating layer being removable from surface of substrate.